

**Features:**

- n Low  $V_{CE(sat)}$  IGBT
- n Low switching losses
- n 10us short circuit capability
- n Fast & soft reverse recovery FRD
- n Temperature sense included
- n Maximum junction temperature 175°C
- n Industry standard package with soldering pins for PCB mounting

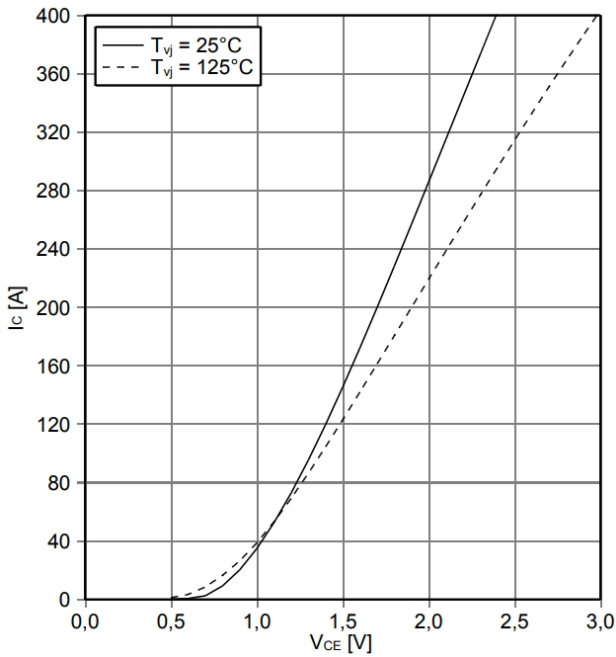
**Typical Applications:**

- n Inverter for Motor Drive

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	VALUE			UNIT
			Min	Type	Max	
$V_{CES}$	Collector-Emitter voltage	$T_j=25^\circ\text{C}$			1200	V
$V_{GES}$	Gate-Emitter voltage	$T_j=25^\circ\text{C}$			$\pm 20$	V
$I_c$	Collector current	Continuous@ $T_c=100^\circ\text{C}$			200	A
$I_{CP}$		$T_j=25^\circ\text{C}$ , 1ms			400	A
$P_c$	Collector power dissipation				1200	W
$T_j$	Junction temperature	/			150	°C
$T_{stg}$	Storage temperature	/	-40		125	°C
$V_{iso}$	Isolation between terminal and copper base	$T_j=25^\circ\text{C}$ , AC: 1minute		2500		V
Screw torque	Mounting(M5)	/	3.0	4.0	5.0	N·m
$I_{CES}$	Zero gate voltage collector current	$T_j=25^\circ\text{C}$ , $V_{CE}=1200\text{V}$ , $V_{GE}=0\text{V}$			5.0	mA
$I_{GES}$	Gate-Emitter leakage current	$T_j=25^\circ\text{C}$ , $V_{CE}=0\text{V}$ , $V_{GE}=\pm 20\text{V}$			$\pm 400$	nA
$V_{GE(th)}$	Gate-Emitter threshold voltage	$T_j=25^\circ\text{C}$ , $V_{CE}=20\text{V}$ , $I_c=1.7\text{mA}$	5.0	6.0	7.0	V
$V_{CE(sat)}$	Collector-Emitter saturation voltage	$T_j=25^\circ\text{C}$ , $V_{GE}=15\text{V}$ , $I_c=200\text{A}$		2.00	2.50	V
		$T_j=125^\circ\text{C}$ , $V_{GE}=15\text{V}$ , $I_c=200\text{A}$		2.40		V
$R_{Gint}$	Integrated Gate Resistor			6		Ω
$C_{ies}$	Input capacitance	$T_j=25^\circ\text{C}$ , $V_{CE}=25\text{V}$ , $V_{GE}=0\text{V}$ , $f=1\text{MHz}$		18		nF
$t_{on}$	Turn-on time	$T_j=125^\circ\text{C}$ , $V_{CC}=600\text{V}$ , $I_c=200\text{A}$ , $V_{GE}=\pm 15\text{V}$ , $R_G=10\Omega$ , Inductive load		85		ns
$t_r$				45		ns
$t_{off}$			Turn-off time		400	
$t_f$		130			ns	
$t_{sc}$	Short circuit withstand time	$T_j=150^\circ\text{C}$ , $V_{CC}=720\text{V}$ , $V_{GE}=\pm 15\text{V}$ , $R_G=10\Omega$	10			μs
$V_F$	Forward on voltage	$T_j=25^\circ\text{C}$ , $I_F=200\text{A}$		2.00	2.20	V
		$T_j=125^\circ\text{C}$ , $I_F=200\text{A}$		2.00		V
$t_{rr}$	Reverse recovery time	$T_j=125^\circ\text{C}$ , $I_F=200\text{A}$		350		ns
		$T_j=150^\circ\text{C}$ , $I_F=200\text{A}$		260		ns
$R_{th(j-c)}$	Thermal resistance(1 device)	IGBT			0.08	°C/W
		FWD			0.1	°C/W
$R_{th(c-f)}$	Contact thermal resistance (1 device)	With thermal compound		0.050		°C/W
$W_t$	Weight				350	g
Outline	454H3P					

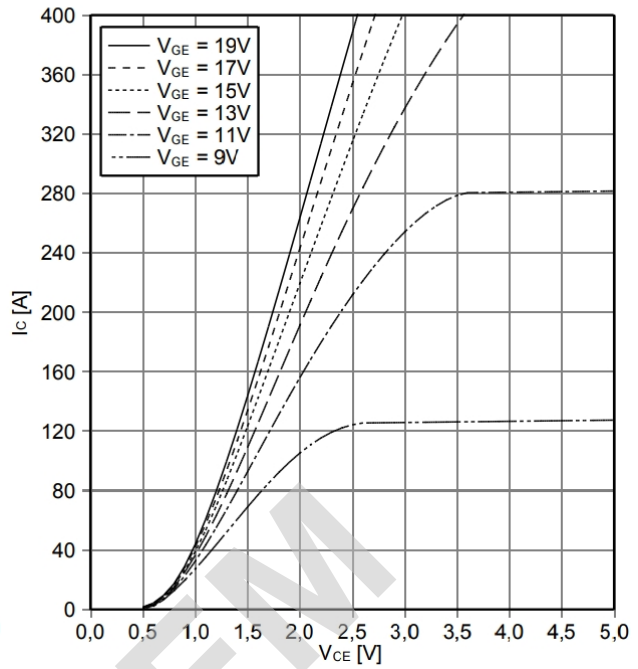
output characteristic IGBT,Inverter (typical)

$I_C = f(V_{CE})$   
 $V_{GE} = 15\text{ V}$



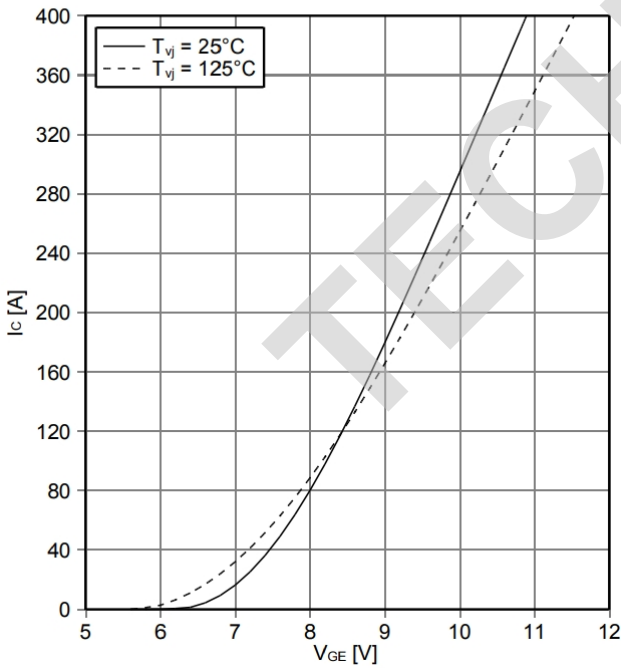
output characteristic IGBT,Inverter (typical)

$I_C = f(V_{CE})$   
 $T_{vj} = 125^\circ\text{C}$



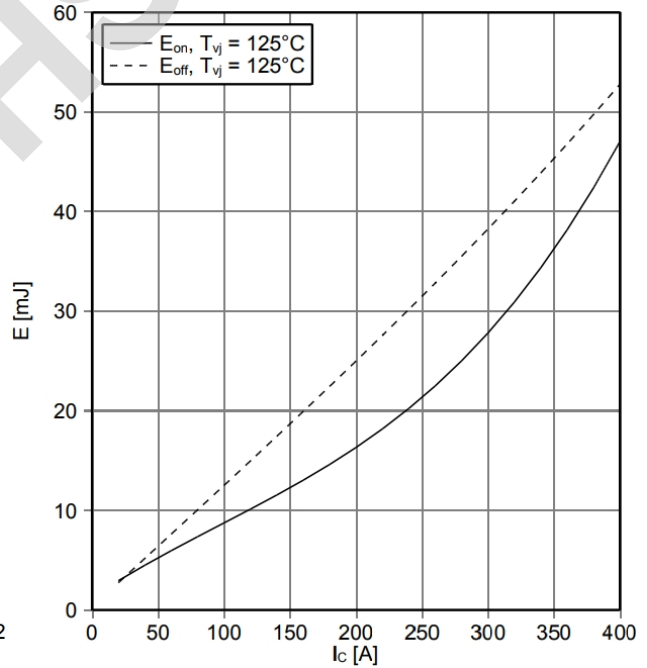
transfer characteristic IGBT,Inverter(typical)

$I_C = f(V_{GE})$   
 $V_{CE} = 20\text{ V}$



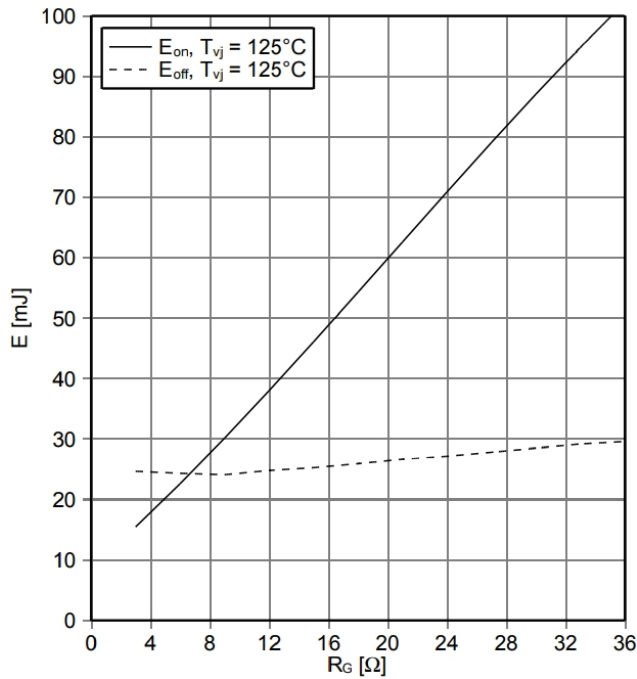
switching losses IGBT,Inverter (typical)

$E_{on} = f(I_C), E_{off} = f(I_C)$   
 $V_{GE} = \pm 15\text{ V}, R_{Gon} = 3.6\ \Omega, R_{Goff} = 3.6\ \Omega, V_{CE} = 600\text{ V}$



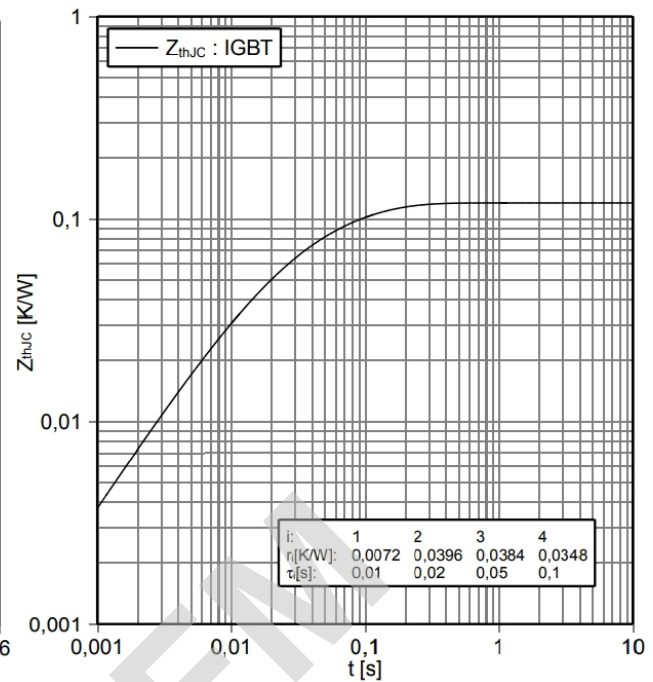
switching losses IGBT, Inverter (typical)

$E_{on} = f(R_G)$ ,  $E_{off} = f(R_G)$   
 $V_{GE} = \pm 15 V$ ,  $I_C = 200 A$ ,  $V_{CE} = 600 V$



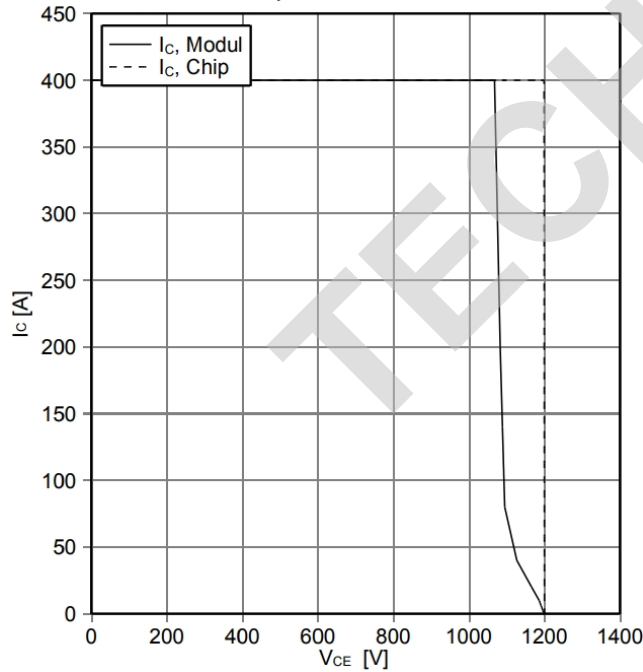
transient thermal impedance IGBT, Inverter

$Z_{thJC} = f(t)$



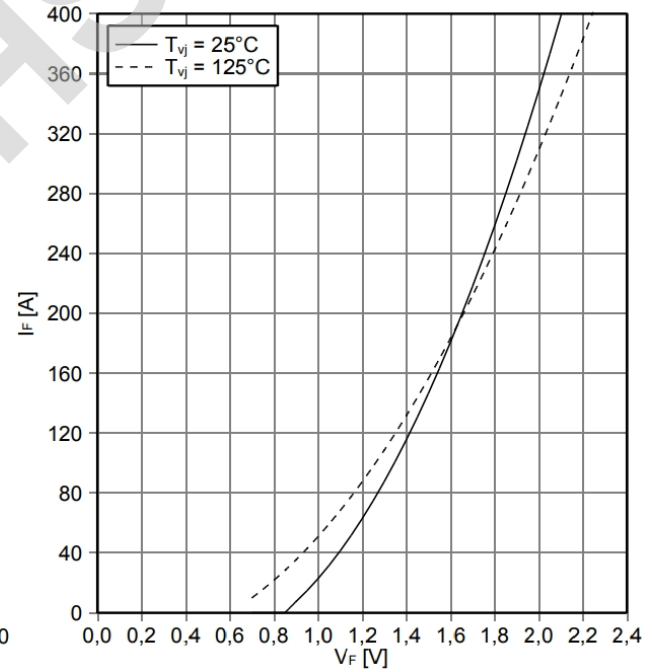
reverse bias safe operating area IGBT, Inverter (RBSOA)

$I_C = f(V_{CE})$   
 $V_{GE} = \pm 15 V$ ,  $R_{Goff} = 3.6 \Omega$ ,  $T_{vj} = 125^\circ C$



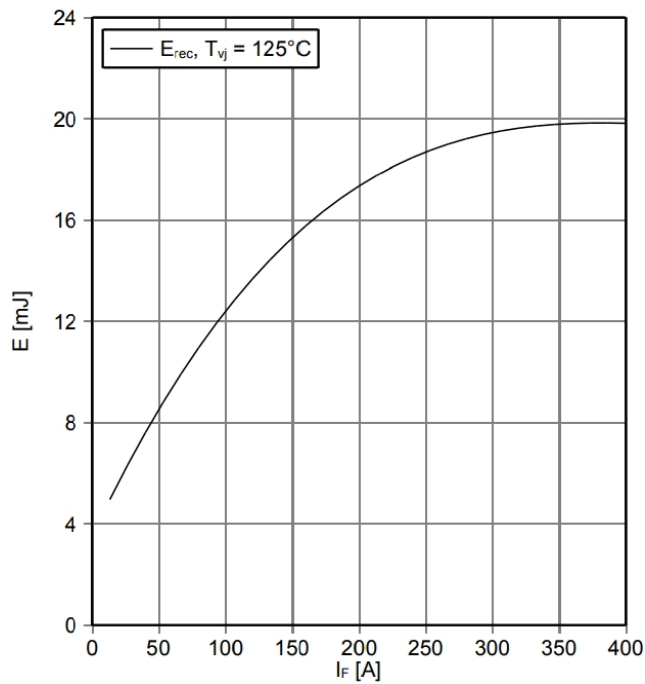
forward characteristic of Diode, Inverter (typical)

$I_F = f(V_F)$



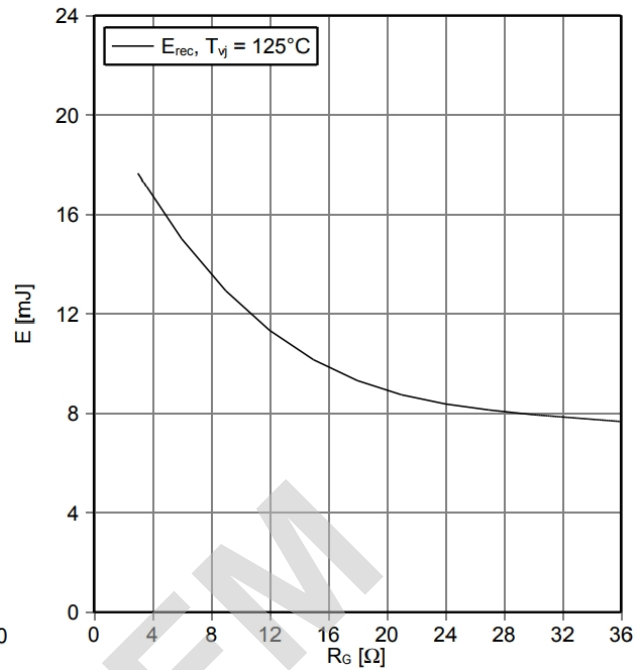
switching losses Diode, Inverter (typical)

$E_{rec} = f(I_F)$   
 $R_{Gon} = 3.6 \Omega, V_{CE} = 600 V$



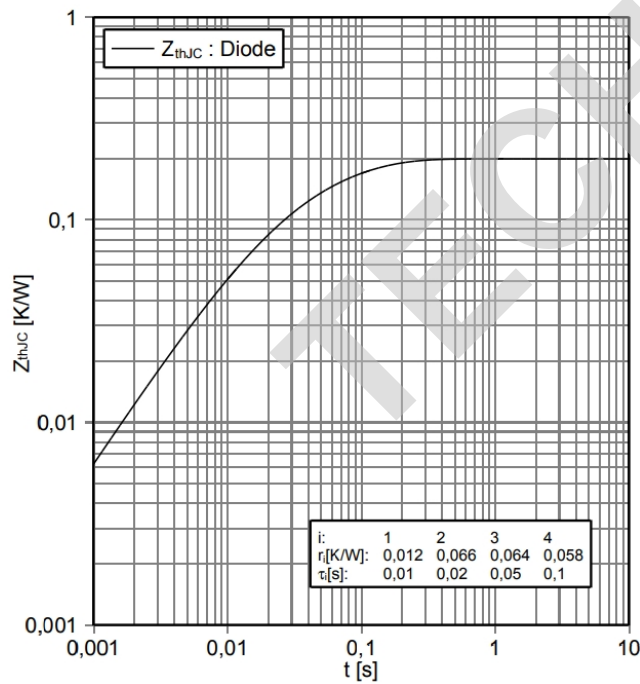
switching losses Diode, Inverter (typical)

$E_{rec} = f(R_G)$   
 $I_F = 200 A, V_{CE} = 600 V$

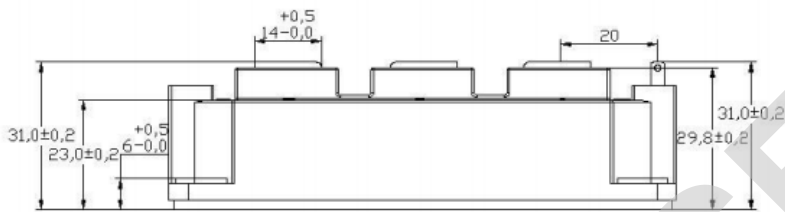
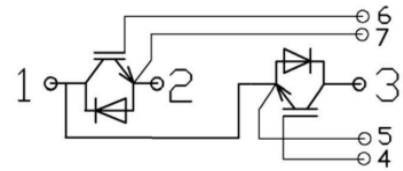
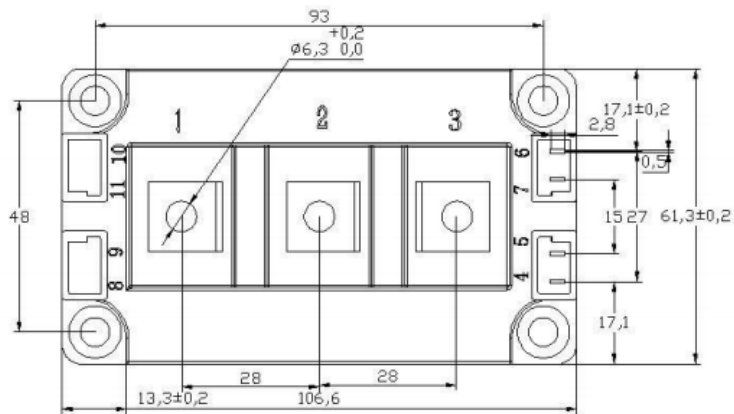


transient thermal impedance Diode, Inverter

$Z_{thJC} = f(t)$



Outline:



TECHSEM